

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S90	2	(*7000000").FN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/21 17:35
S89	106	S87 and (wafer adj level wafer-level wafer\$level wafer adj scheme wafer- scheme wafer\$scheme)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 17:34
S88	7532	(wire adj bond\$3 wire-bond \$3 wirebond\$3 wire\$1bond \$3 lead adj frame lead- frame leadframe lead \$1frame) with (lid cap cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 17:33
S87	2371	S86 and @ad<="20030225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 17:33
S86	4225	S85 and S83	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 17:32
S85	511216	((("257") or ("438")).CLAS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/21 17:32
S84	320450	*257"/	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 17:32
S83	7532	(lid cap cover) and (wire adj bond\$3 wire-bond\$3 wirebond\$3 wire\$1bond\$3 lead adj frame lead-frame leadframe lead\$1frame) with (lid cap cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 17:32

S82	76	S81 and @ad<="20030225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 17:14
S81	219	MEMS with (lid cap cover) and (wire adj bond\$3 wire- bond\$3 wirebond\$3 wire \$1bond\$3 lead adj frame lead-frame leadframe lead \$1frame) with (lid cap cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:56
S80	56	S74 NOT S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:50
S79	80	S77 and @ad<="20030225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:42
S78	41	S74 and @ad<="20030225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:41
S77	261	S75 NOT S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:40
S76	0	(wire adj bond\$3 wire-bond \$3 wirebond\$3 wire\$1bond \$3) with (wafer adj scheme wafer-scheme wafer \$scheme)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:40
S75	276	(wire adj bond\$3 wire-bond \$3 wirebond\$3 wire\$1bond \$3) with (wafer adj level wafer-level wafer\$level)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:40

S74	97	(lead adj frame lead-frame leadframe lead\$1frame) with (wafer adj level wafer-level wafer\$level)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:40
S73	0	(wire adj bond\$3 wire-bond \$3 wirebond\$3 wire\$1bond \$3) with (wafer adj scheme wafer-scheme wafer \$lscheme)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:38
S72	0	MEMS and (wire adj bond\$3 wire-bond\$3 wirebond\$3 wire\$1bond\$3) with (wafer adj scheme wafer-scheme wafer\$lscheme)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:37
S71	0	(lead adj frame lead-frame leadframe lead\$1frame) with (wafer adj scheme wafer-scheme wafer\$lscheme)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:36
S70	0	MEMS and (lead adj frame lead-frame leadframe lead \$1frame) with (wafer adj scheme wafer-scheme wafer \$lscheme)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:36
S69	18	("4541003"   "4630095"   "4769345"   "4771214"   "5610431"   "5614785"   "5650568"   "5837562"   "6225145"   "6277666"   "6323550"   "6338284"   "6806557").PN. OR ("6929974").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/21 16:23
S68	6	("5293511"   "5856914"   "6303986"   "6455927"   "6929974").PN. OR ("7098535").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/21 16:20
S67	38	("5824186"   "6297072").PN. OR ("6448109").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/21 16:16
S66	37	MEMS and (wire adj bond\$3 wire-bond\$3 wirebond\$3 wire\$1bond\$3) with (wafer adj level wafer-level wafer \$level)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:09

S65	28	MEMS and ((electric\$2 conduct\$3) near5 (lead terminal) with (wafer adj level wafer-level wafer \$level))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:06
S64	5	MEMS and (lead adj frame lead-frame leadframe lead \$1frame) with (wafer adj level wafer-level wafer \$level)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/21 16:03

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